

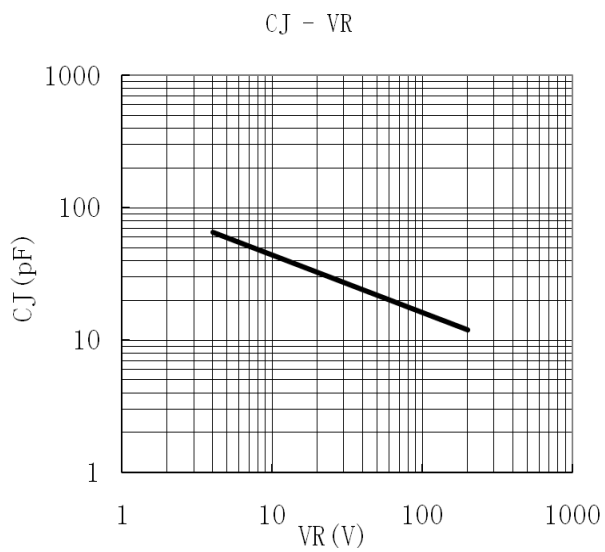
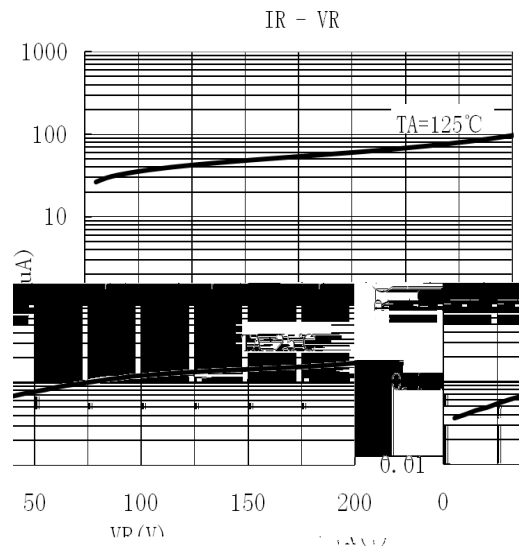
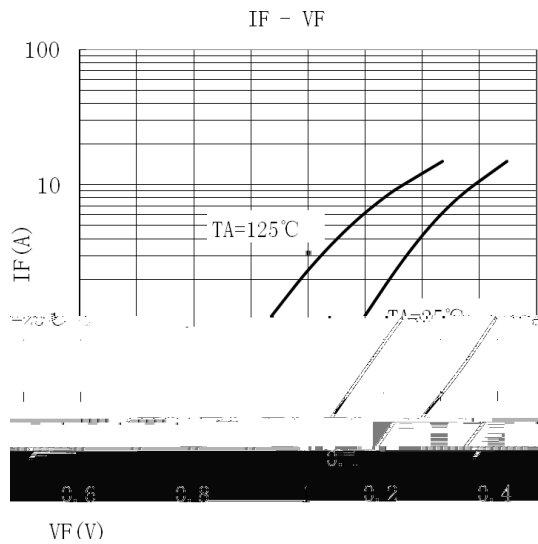
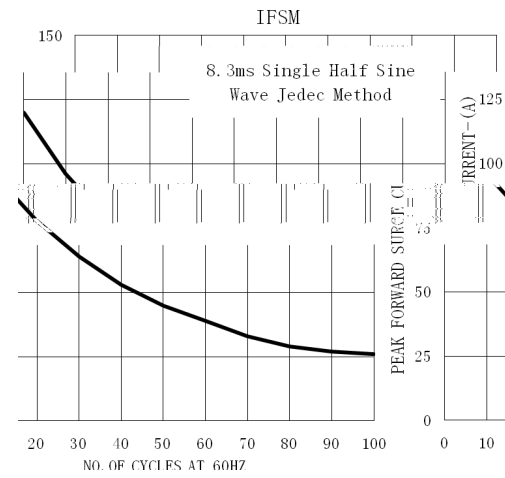
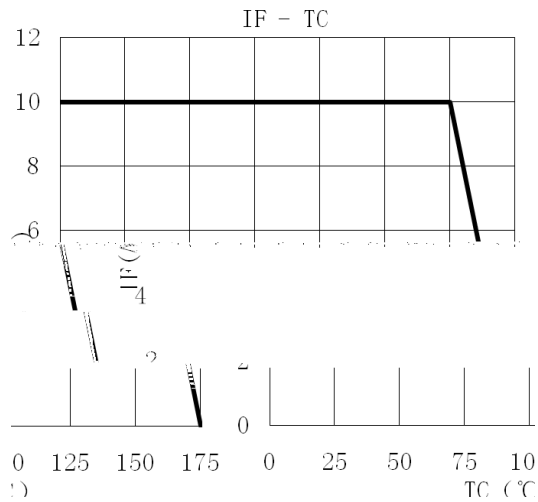
/ Absolute Maximum Ratings(Ta=25)

Parameter	Symbol	Rating	Unit
Peak Repetitive Reverse Voltage	V_{RRM}	200	V
Average Rectified Forward Current	$I_{F(AV)}$	10	A
Peak Repetitive Forward Current	I_{FRM}	10	A
Non Repetitive Peak Surge Current	I_{FSM}	150	A
Peak Repetitive Reverse Surge Current	I_{RRM}	0.5	A
Thermal Resistance Junction to Case	$R_{\theta Jc}$	2.5	/W
Junction and Storage Temperature Range	$T_j T_{stg}$	-65~150	

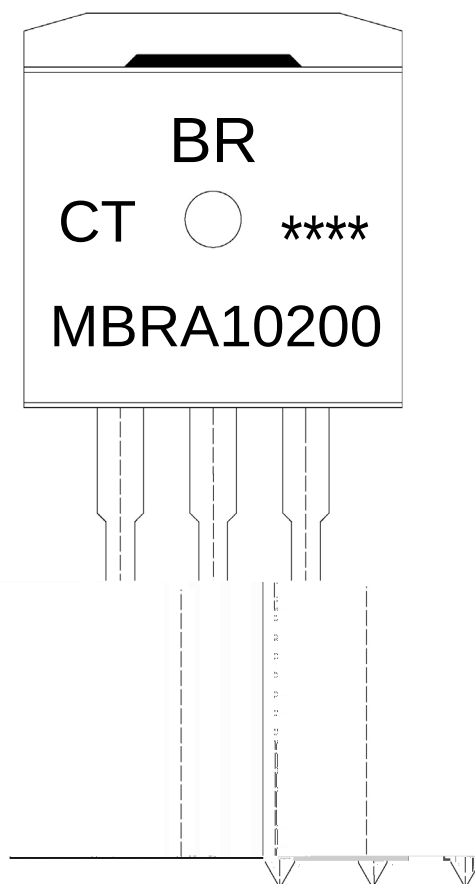
/ Electrical Characteristics(Ta=25)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Reverse Voltage	V_R		200			V
Forward Voltage	V_{FM}	$I_F=5.0A(T_C=25^{\circ}C)$			0.99	V
		$I_F=5.0A(T_C=125^{\circ}C)$			0.87	V
Instantaneous Reverse Current	I_{RM}	$V_R=200V(T_C=25^{\circ}C)$			0.15	mA
		$V_R=200V(T_C=125^{\circ}C)$			150	mA
Voltage Rate of Change	dv/dt				10000	V/ μ s

/ Electrical Characteristic Curve



/ Marking Instructions



Б " X

EU X

PEUD43533 X

FW:

---- X

Note:

BR:

MBRA10200 X

CT:

****:

BR

CT

FW

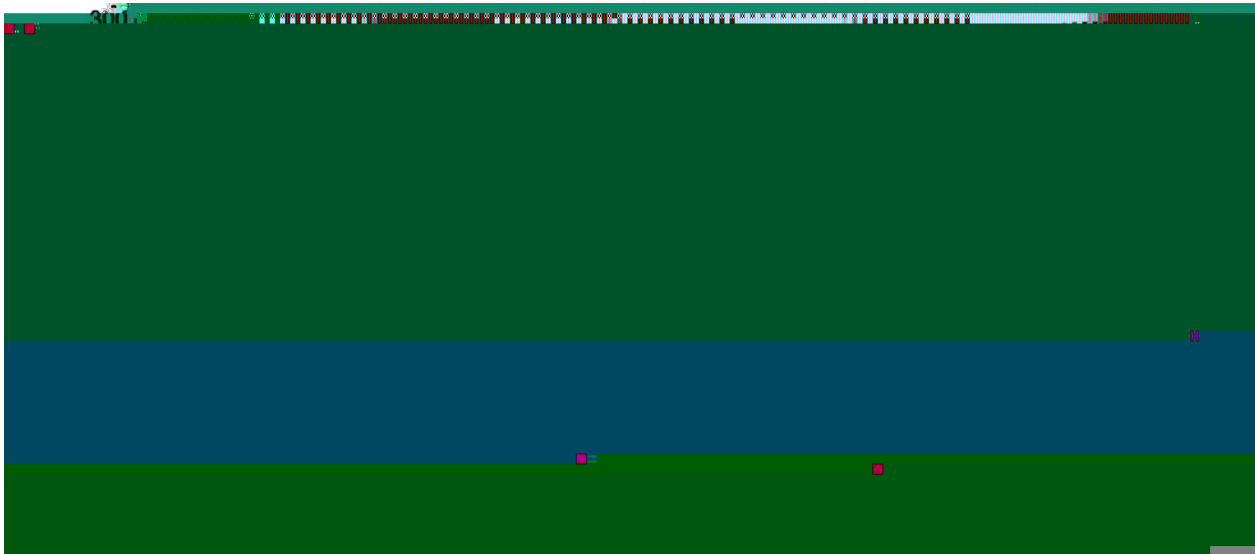
Company Code

Product Type.

Internal Structure

Lot No. Code, code change with Lot No.

() / Temperature Profile for Dip Soldering(Pb-Free)



б " χ

1. 1. 25~150 °C, Time: 60~90sec;
2. 2. 255 °C, Duration: 5 °C 0.5sec;
3. 3. Cooling Speed: 2~10 °C/sec.

Note:

1. Preheating: 25~150 °C, Time: 60~90sec.
2. Peak Temp.: 255 °C, Duration: 5 °C 0.5sec.
3. Cooling Speed: 2~10 °C/sec.

/ Resistance to Soldering Heat Test Conditions

□ ý χ 270 ° 5 ± 'H ¿ χ 10 ° 1 sec. Temp.: 270 ± 5 Time: 10 ± 1 sec

/ Packaging SPEC.

„ 1 γ ƒ / TUBE

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)		
	Units/Tube 只/套管	Tubes/Inner Box 套管/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Tube 套管	Inner Box 盒	Outer Box 箱

/ Notices